

OPEN PIN FIELD ARRAY SEAF SERIES

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?SEAF

Insulator Material: Black LCP
Contact Material:
Copper Alloy

Current Rating:

Operating Temp Range: -55°C to +125°C

Plating: Au over 50μ" (1,27μm) Ni

Contact Resistance:

 $5.5 \text{ m}\Omega$ Working Voltage: 240 VAC **Mated Cycles:**

RoHS Compliant: Yes

Processing:

Max Processing Temp: 230°C for 60 seconds, or 260°C for 20 seconds 3x Lead-Free Solderable:

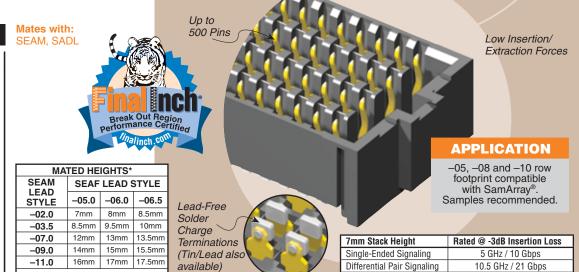


DIFFERENTIAL **APPLICATION**



Т	
ARRAY	PAIR COUNT
50x10	125
50x8	100
40x10	100
40x8	80
40x6	60
30x10	75
30x8	60
30x6	45
20x10	50
20x8	40
20x10	25

Note: Some sizes, styles and options are non-standard, non-returnable.



-20, -30,

-40[°]. –50

→ (1,27) .050

9 9 9 9 9 9 9 9 9

NO. PINS

PER ROW

Processing conditions will affect

mated height.

No. of rows

.050

(0,53) .021

Specify LEAD **STYLE** from chart

88888888888

LEAD

STYLE

-S = 30µ"

(0,76µm) Gold on contact area Matte Tin on

PLATING

OPTION

=Four Rows -05=Five solder tail Rows (Lead Style -05.0 only)

.050

-06=Six Rows (Lead Style -05.0 only) -08 =Eight

NO. OF

ROWS

-04

Rows -10=Ten Rows

= Lead-Free Tin Alloy 95.5% Sn/ 3.8% Ag/0.7% Cu Solder Charge

SOLDER

TYPE

Performance data for other stack heights

available at www.samtec.com?SEAF

= Alignment Pins (Recommended. Arrays will not self-center on solder pads)

> = Polyimide film Pick & Place Pad

OPTION

– A

-TR =Tape & Reel

(1,27) .050	<u> </u>	(0,20) A .008
	0000000 0000	
(1,12)	/ /	Ĭ
	ons x (1,27) .050 + (3,58	8) .141—>

No. of positions x (1,27) .050 + (5,82) .229

LEAD Α STYLE -05.0(5,05) .199 (6,05) .238 -06.0 -06.5 (6,55) .258

Due to technical progress, all designs, specifications and components are subject to change without notice.

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